



TPC 612

RR-T612-20PK-R1



TPC 612 is the next generation of CPU cooler thanks to new vertical vapor chamber technology combined with four 6mm heat pipes. A nickel plated, pure polished copper base spreads heat into a tall, aluminum alloy heat sink ensuring optimal cooling. TPC 612 has a slimmer heatsink than the TPC 812 to support overclocking memory modules.

Features

- The TPC 612 uses 2 separate cooling technologies to transfer heat – heat pipes and vertical vapor chambers.
- 100% pure polished copper base – combined with improved soldering technologies for the best thermal transfer.
- Special fin design – heatsink receives concentrated cold airflow.
- Slim heatsink provides great compatibility for overclocking memory modules with tall heat spreader.
- Clip-on fan mounting bracket

Package Information

EAN Code	4719512038833
UPC Code	884102018213
Package Dimensions	189 x 110 x 250 mm (7.4 x 4.3 x 9.8 in)
Carton Dimensions	470 x 395 x 288mm (18.5 x 15.6 x 11.3 in)
Unit / Carton	8
Carton / Pallet	42

Specifications

CPU Socket	Intel® LGA 2011/1366/1156/1155/775
	AMD FM1/AM3+/AM3/AM2+/AM2
Dimensions	145 x 97 x 161.6 mm (5.7 x 3.8 x 6.4 in)
Heat Sink Dimensions	134 x 85 x 161.6 mm (5.3 x 3.4x 6.4 in)
Heat Sink Material	Copper Base / 2 Vapor Chambers
	4 Heatpipes / Aluminum Fins
Heat Sink Weight	640g (1.72 lb)
Heat Pipe Dimensions	Ø6mm
Fan Dimensions	120 x 120 x 25mm (4.7 x 4.7 x 1 in)
Fan Speed	600 ~ 2,000 RPM (PWM) ± 10%
Fan Air Flow	24.9 ~ 82.9 CFM ± 10%
Fan Air Pressure	0.3 ~ 2.7 mm H ₂ O ± 10%
Fan Life Expectancy	40,000 hrs
Noise Level	9 ~ 36 dBA
Bearing Type	Rifle Bearing
Connector	4-Pin
Fan Weight	122g (0.33 lb)
Weight	762g (2.05 lb)

Warranty

2 years



Appendix

Photo taken: July 4, 2012



Synergy cooling – Vapor chamber +
Heatpipe



Vertical vapor chamber



Pure polished copper base



Special fin design



Improved fan mounting system

Note: Photos may differ slightly from the final product.